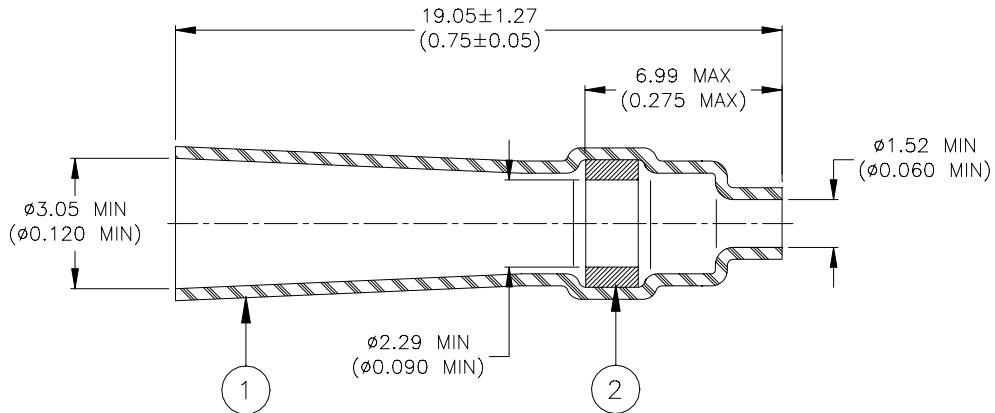


SPECIFICATION CONTROL DRAWING



MATERIALS

1. INSULATION SLEEVE: Heat shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. SOLDER PREFORM WITH FLUX:
 - SOLDER: TYPE Sn63 per ANSI J-STD-006.
 - FLUX: TYPE ROL1 per ANSI J-STD-004.

APPLICATION

1. This part is designed to attach a 20 or 22 AWG lead to a solder dipped pin 1.02 (0.040) in diameter.
2. Part may be installed with infrared or convection heating technique.

tyco Electronics		Raychem		Tyco Electronics Corporation 300 Constitutional Drive Menlo Park, CA 94025 USA		TITLE : SOLDERSLEEVE, LEAD/ PIN TERMINATION	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.				DOCUMENT NO.: D-141-56			
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A		ANGLES: N/A ROUGHNESS IN MICRON		Tyco Electronics reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		DATE: 04-Apr.-01	
DOC ISSUE: 1		DRAWN BY: M. FORONDA		CAGE CODE: 06090		REPLACES: N/A	
DCR NUMBER: D010067		PROD. REV.: A		SCALE: None		SIZE: A	
SHEET: 1 of 1							

If this document is printed it becomes uncontrolled. Check for the latest revision.

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)